

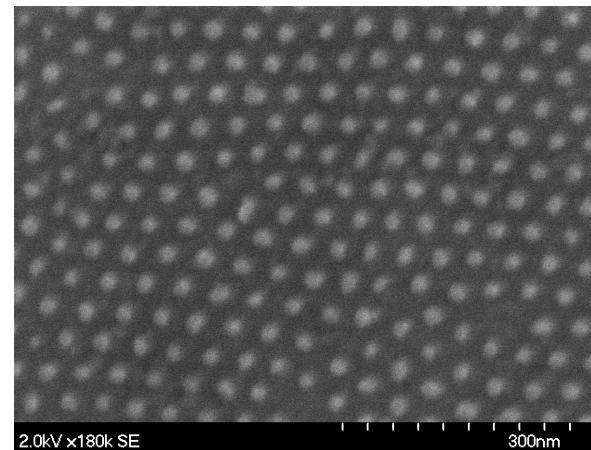
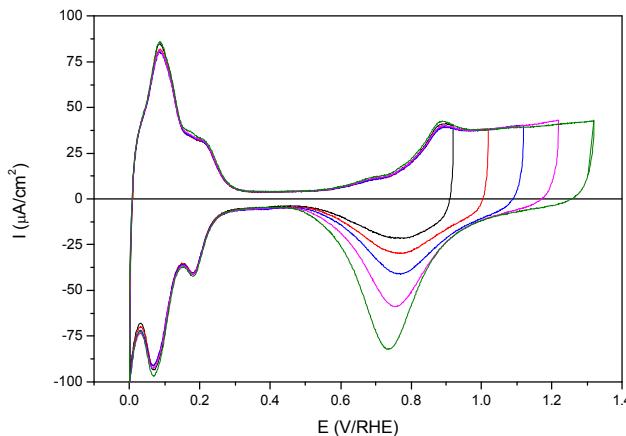
Model Electrode Structures for Studies of Electrocatalyst Degradation

Ronald Goeke,

Sandia National Laboratories, University of New Mexico

Abhaya Datye, Plamen Atanassov

University of New Mexico



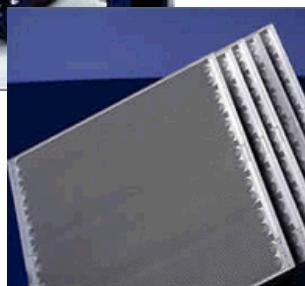
Fuel Cells

Polymer Electrolyte Membrane (PEM) Fuel Cells

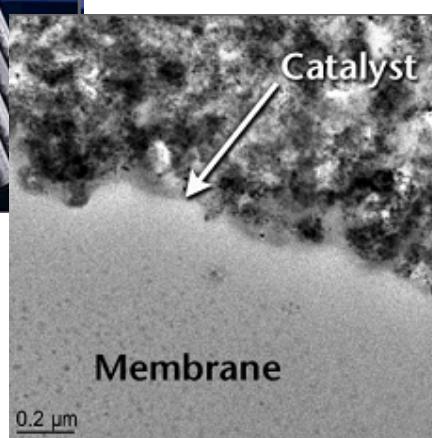


Limitations are primarily cathode requirements
Oxygen Reduction Reaction (ORR)
Pt most effective catalyst
Pt expensive (minimize)
Catalyst degradation

FC System



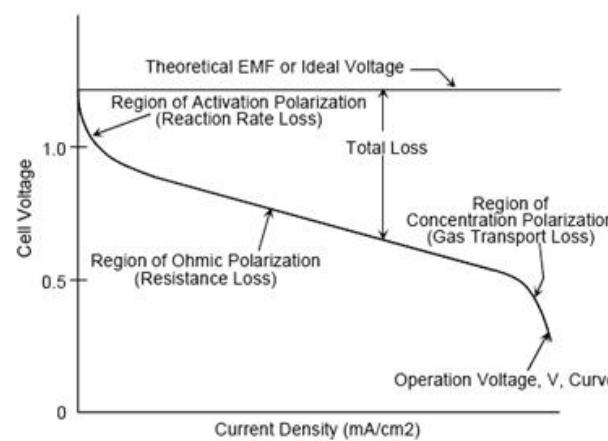
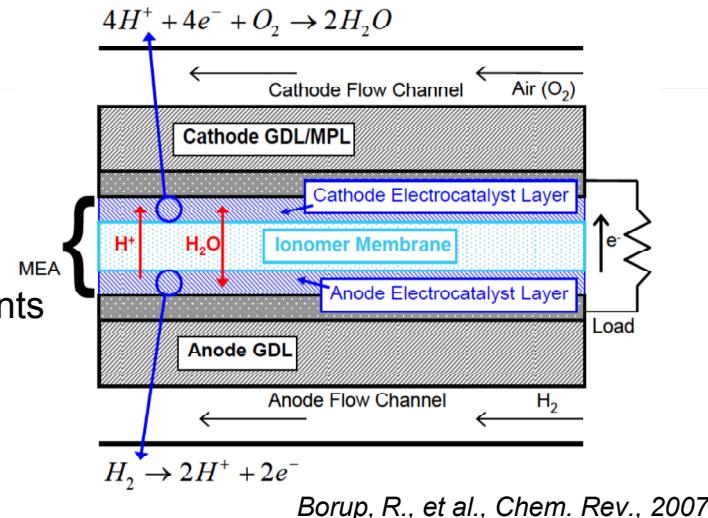
MEA stacks



Catalyst / Membrane

$0.2 \mu\text{m}$

Potential replacement for the internal-combustion engine and portable power. - efficient, clean and low temperature $\sim 80^\circ\text{C}$

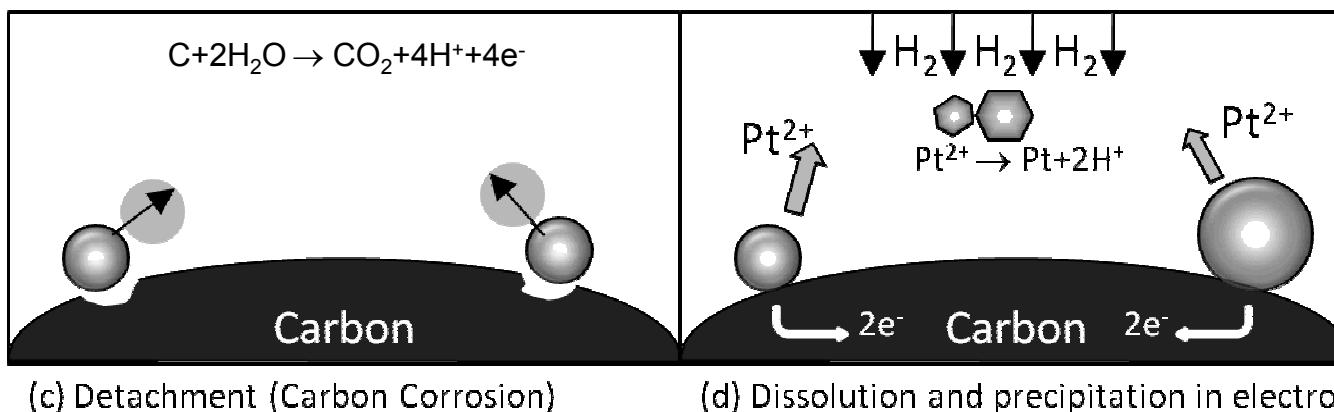
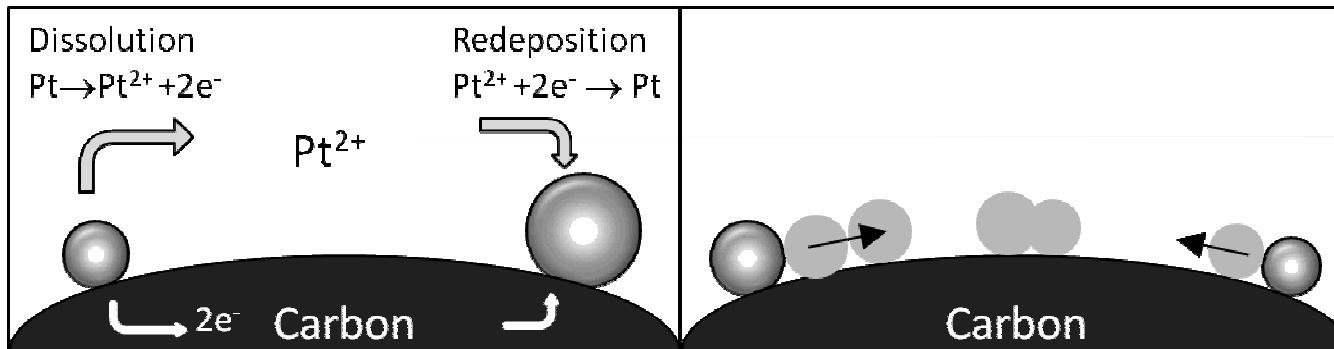


PEM Fuel Cells

Pt Catalyst Degradation Mechanisms

Sintering/Coarsening

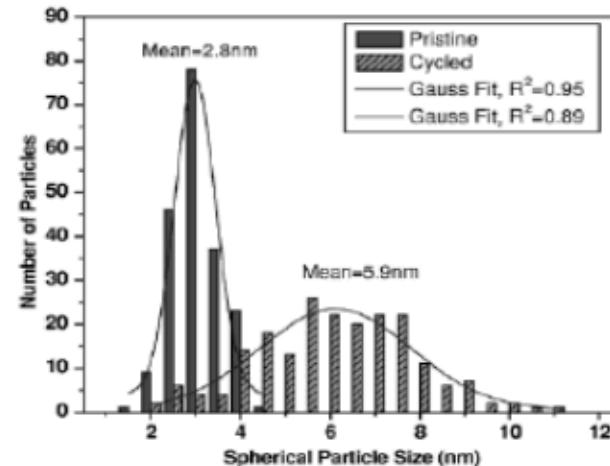
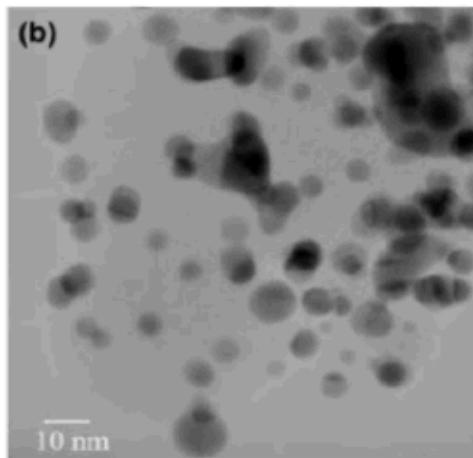
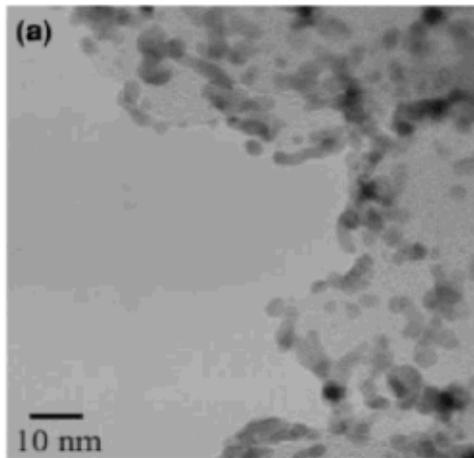
Surface Area Loss



Corrosion (catalyst / support)
Material Loss

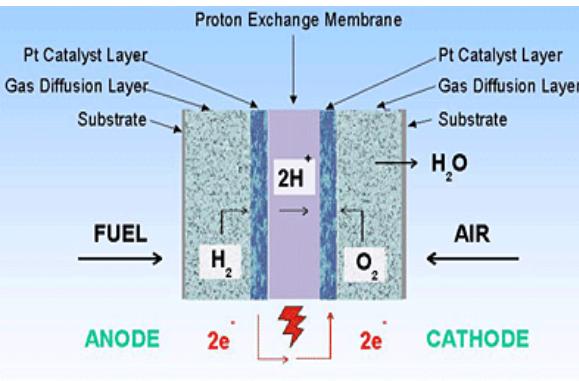
PEM Fuel Cells

Typical Catalyst Sintering Studies



P. J. Ferreira, et. al. *J. Electrochem. Soc* (2005)

- Average Particle size increased from 2.8 nm to 5.9 nm (0,000 cycles 0.6 – 1.0V)
Sintering mechanism proposed by particle size distribution

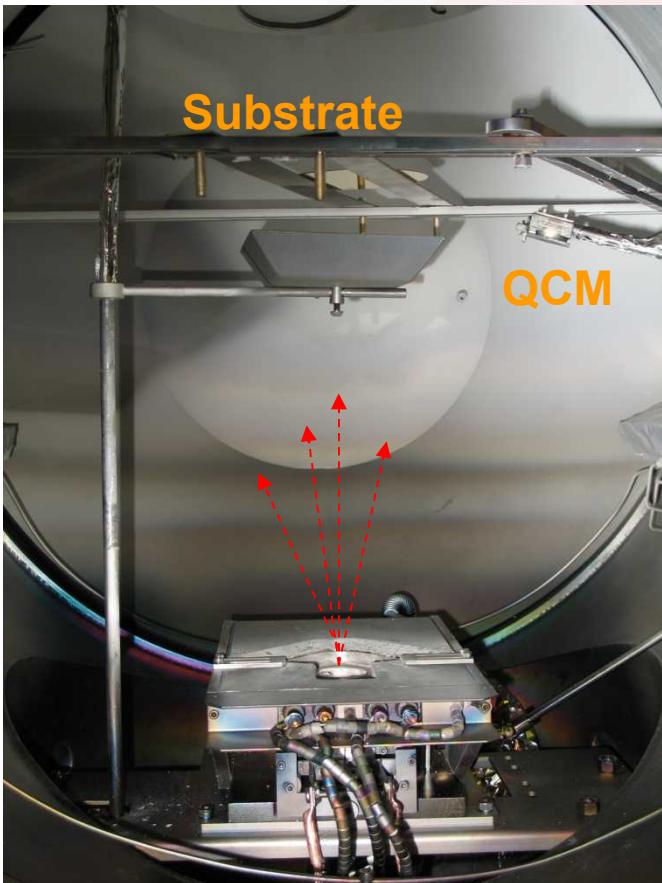


Johnson Matthey Fuel Cells
the power within

- Fuel cell catalyst are a complex mixture of metal particles, carbon support, gas diffusion layer and electrolyte.
- Destruction of the FC/MEAs are required to study the degradation process (statistical). Time consuming and costly
- A 2D Model Electrode is needed to bridge the gap between model single crystal surfaces and powder catalyst

Model Catalyst Fabrication

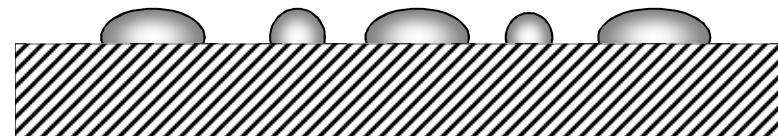
Ultra-thin Metal Deposition



Base Pressure: 1×10^{-7} torr
Evaporation rate 0.1 \AA/s
Deposit directly on Electrode
Pt heated to $\sim 1800^\circ\text{C}$
Pt purity = 0.99999



Growth of wetting films (Layer by Layer growth)



Growth of non-wetting films (Volmer-Weber growth)

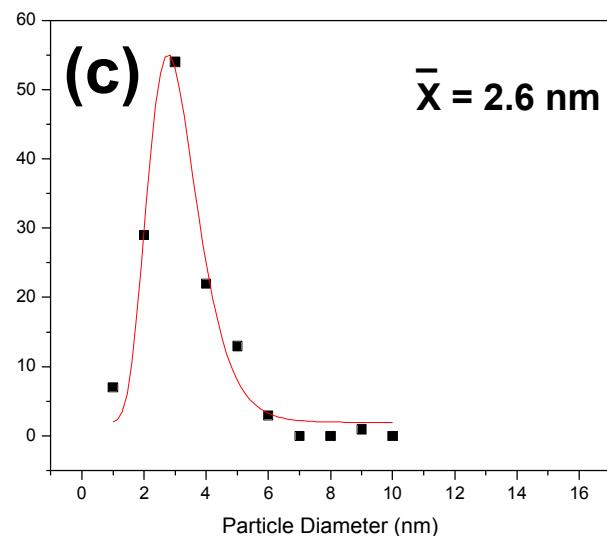
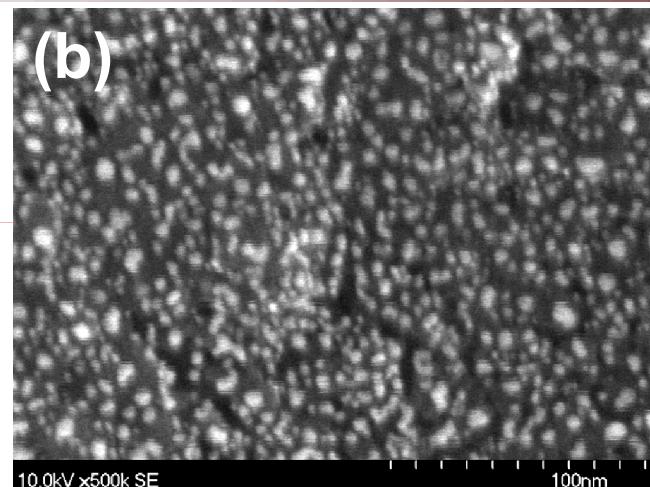
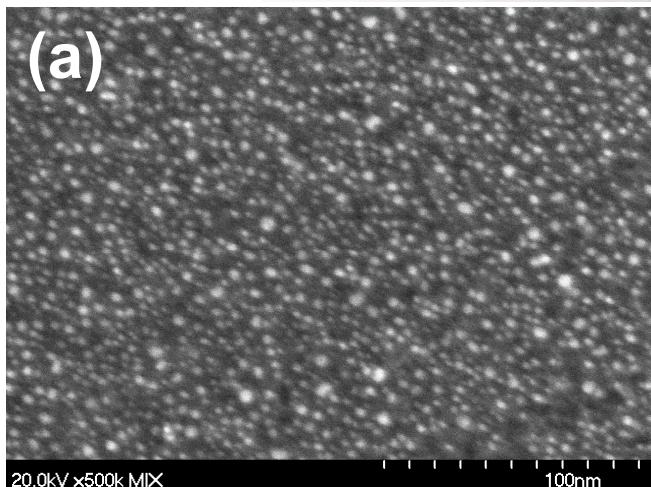
Pt on Carbon is non-wetting

- mass/area loading will be utilized instead of film thickness

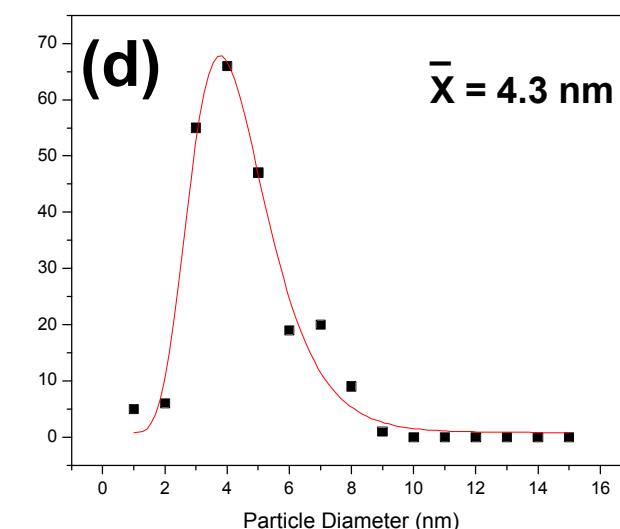
$$\rho_{\text{Pt}} = 21.4 \text{ g/cc} \quad \rightarrow \quad 1 \text{ nm film} = 2.1 \mu\text{g/cm}^2$$

Pt particle Size Control on GC

Loading Affect PSD (800°C anneal)



$(1.1 \mu\text{g Pt/cm}^2)$



$(2.1 \mu\text{g Pt/cm}^2)$

Model Electrodes

Characterization Cycle

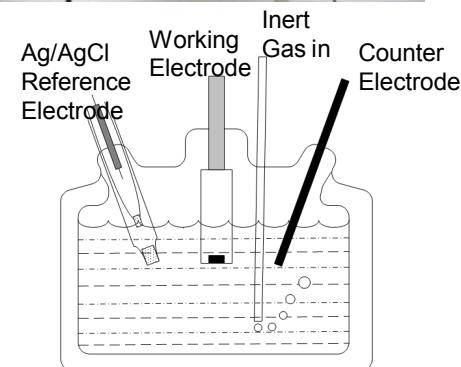
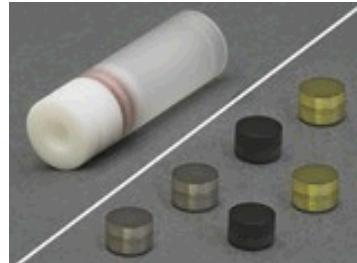
High Resolution
Field Emission
SEM imaging
Hitachi 5200



Electrochemical
Activity
Rotating Disk
Electrode (RDE)

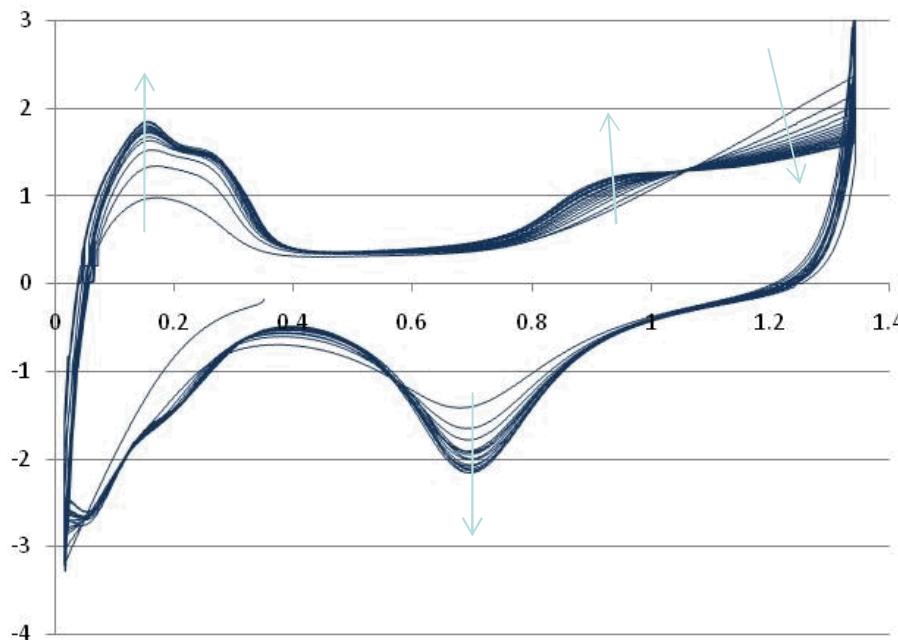


Use a removable
5mm Glassy Carbon
Electrode
from Pine Research
Instrumentation

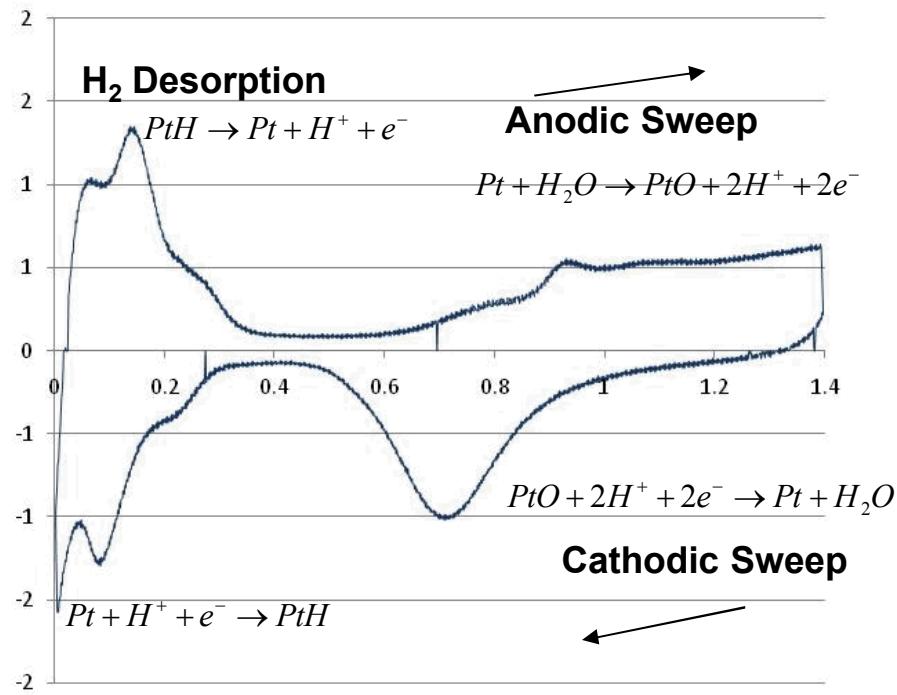


Electrode Cleaning Cycles

Initial Conditioning / Pt Cyclic Voltamogram

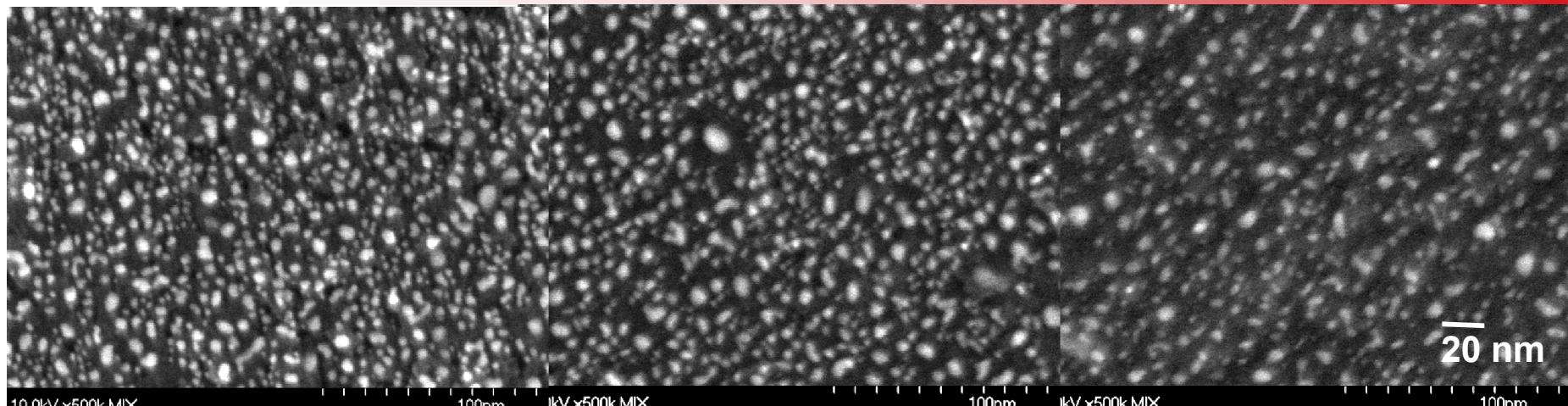


Ar saturated 0.1M HClO₄ at 20°C
500 mV/sec

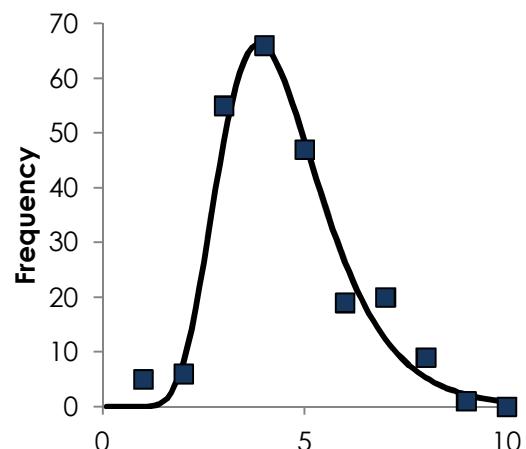


Pt (2.1 $\mu\text{g}/\text{cm}^2$) 800°C Anneal

Aged in Ar saturated 0.1M HClO₄ at 20°C



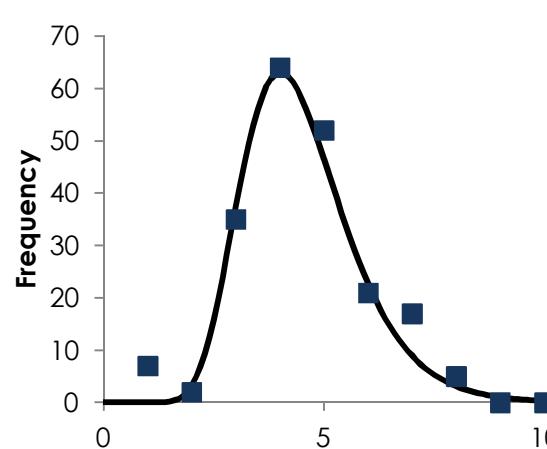
After 800°C anneal



$d = 4.3 \text{ nm}$

Log normal distribution

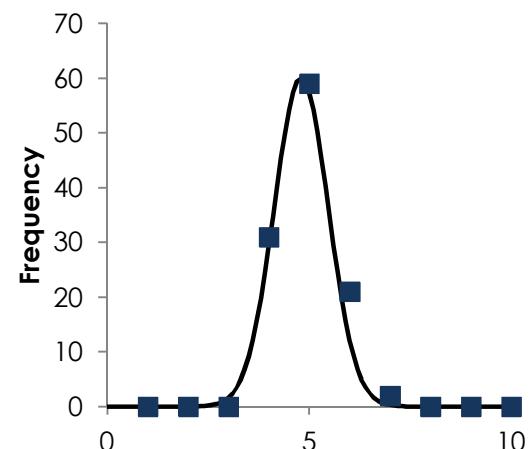
Initial Conditioning



$d = 4.4 \text{ nm}$

Log normal distribution

500 cycles 0.6 – 1.2V RHE



$d = 4.9 \text{ nm}$

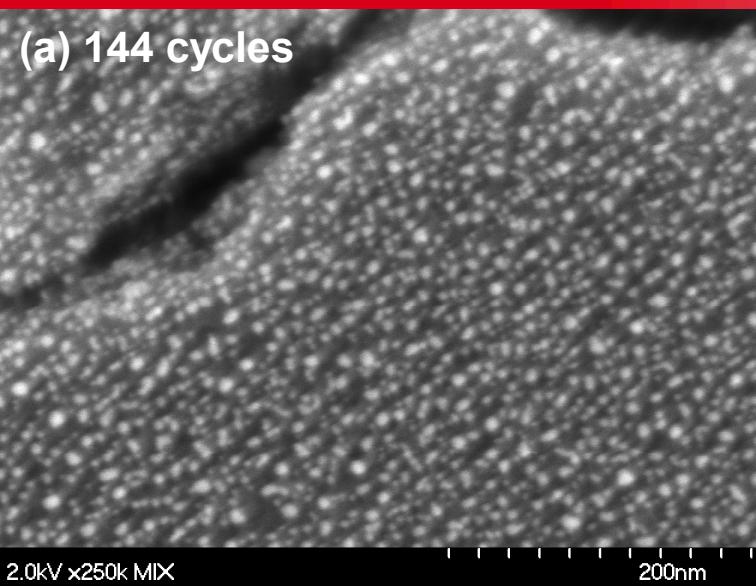
normal distribution

Ostwald Ripening & dissolution?

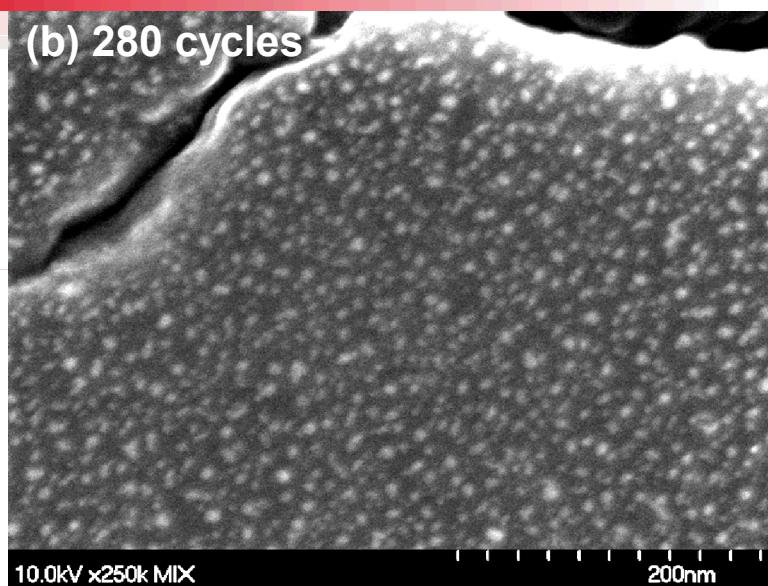
Fixed Location Study

Aging (cycled 0.6 – 1.2 VRHE)

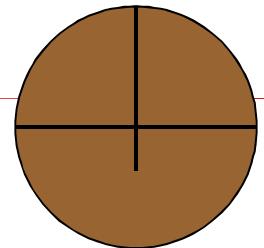
(a) 144 cycles



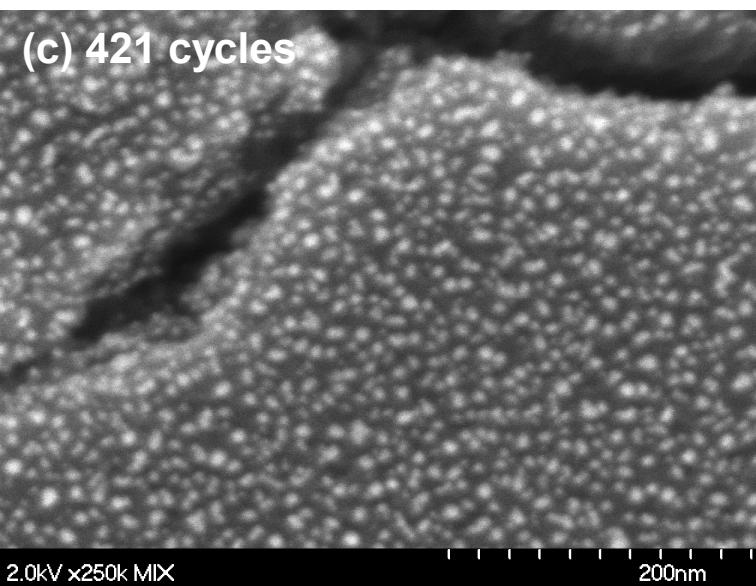
(b) 280 cycles



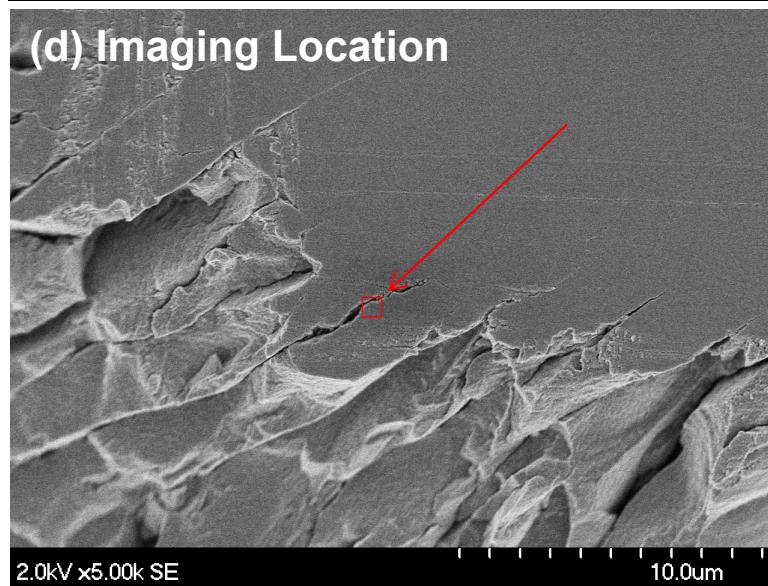
Diamond scribed reference marks



(c) 421 cycles



(d) Imaging Location

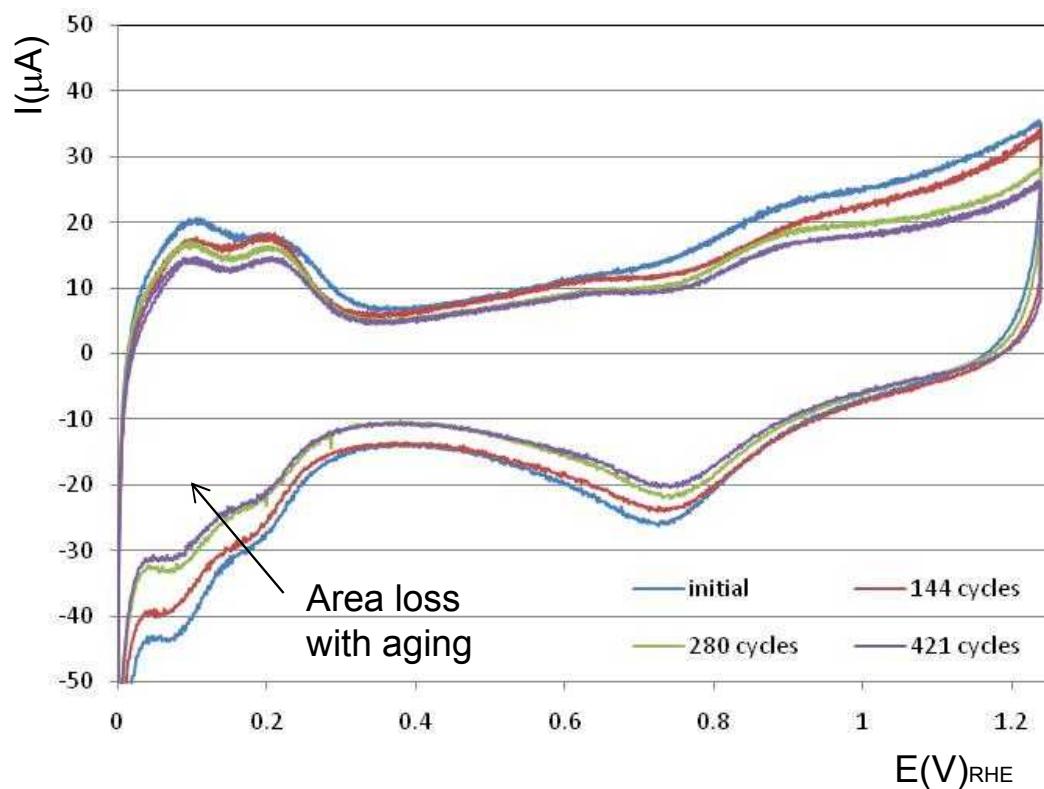


In Ar purged
0.1M HClO₄
50 mV/s

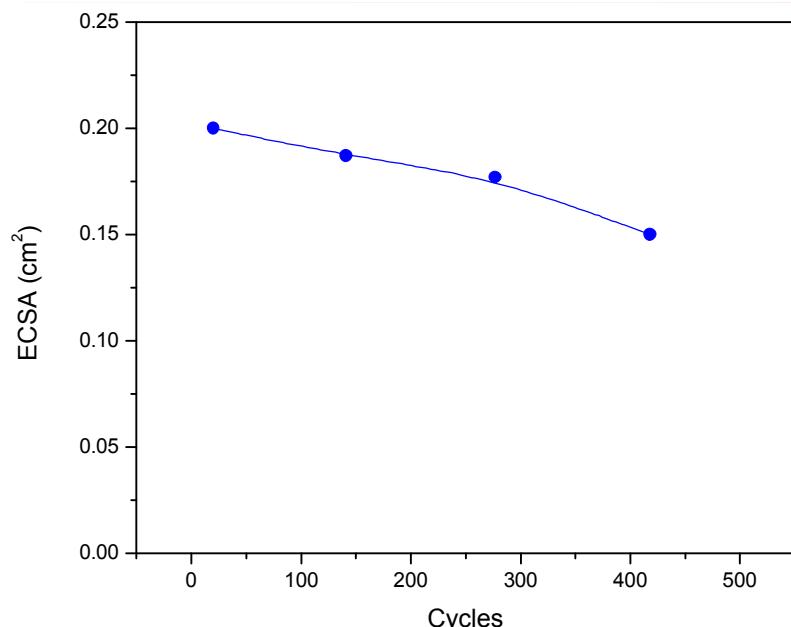
Pt/GCE Repeat Cycling

Aging (cycled 0.6 – 1.2 V_{RHE}) Ar

Cyclic Voltamograms show area loss



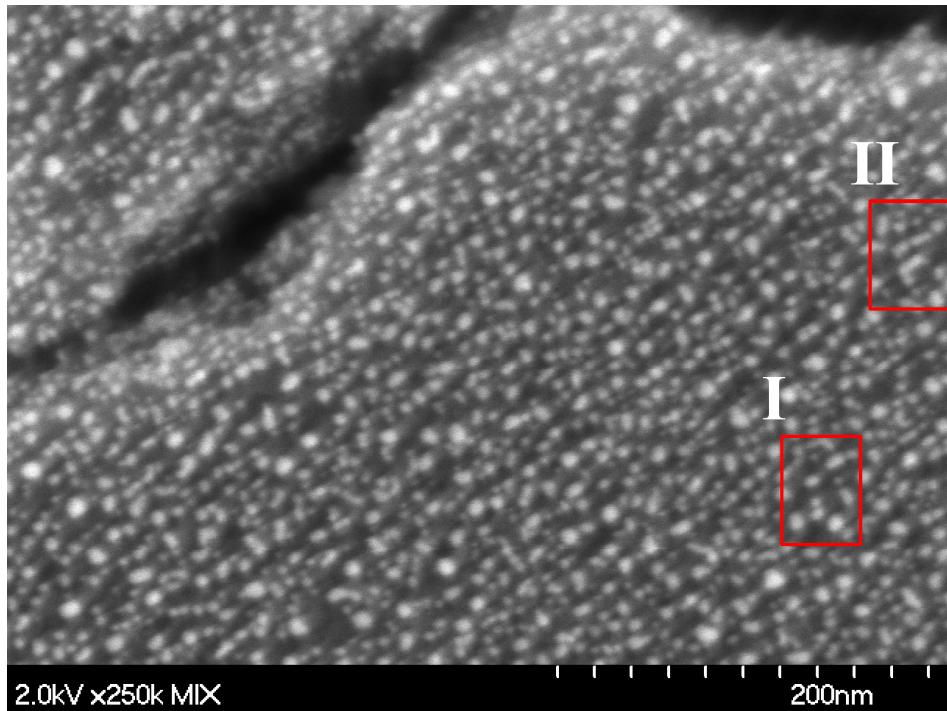
Electrochemically Active Surface Area (ECSA) from CO stripping



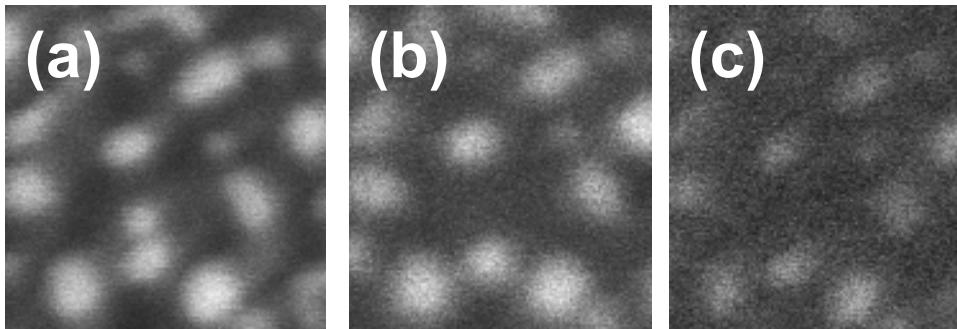
2.1 $\mu\text{g Pt/cm}^2$ and 800°C anneal

Particle Migration/Coalescence

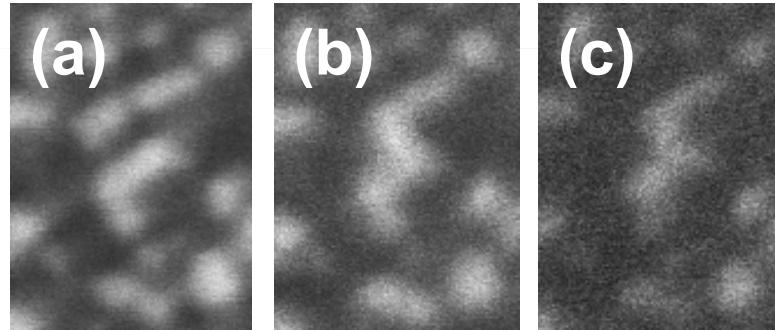
Sintering Observations



Region I



Region II

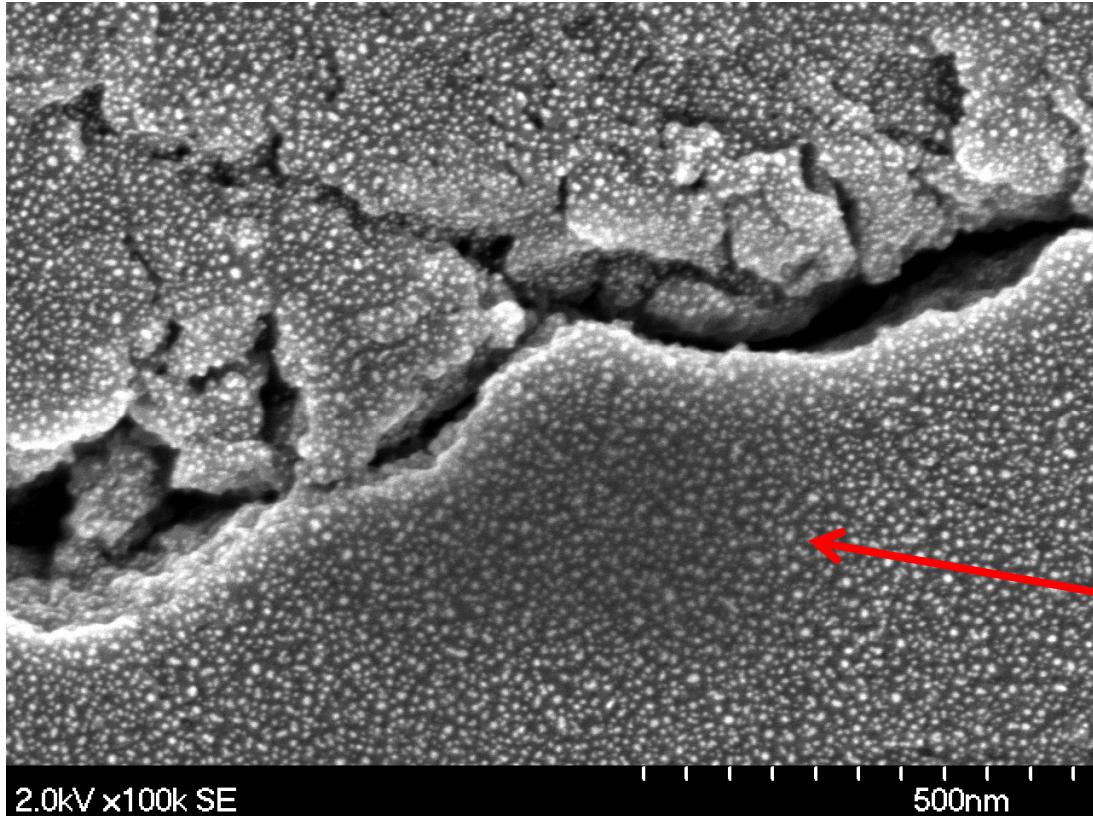


Formation of elongated shapes

Agglomeration, followed by slow sintering

SEM imaging residue

Residue limits imaging cycles



**Previous imaging
location still evident
after testing**

**Does this affect
future sintering?**

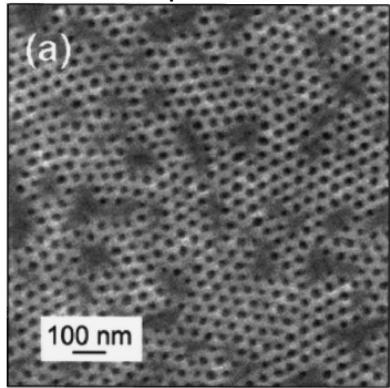
Control over initial particle position and size required
to eliminate repeat imaging of the same location!

Diblock Copolymers

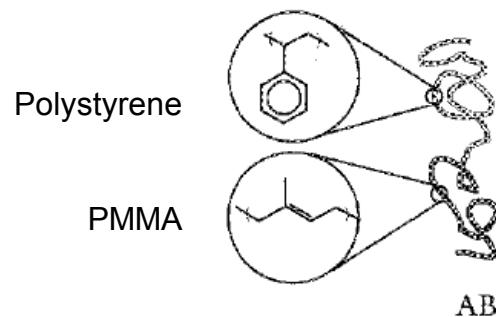
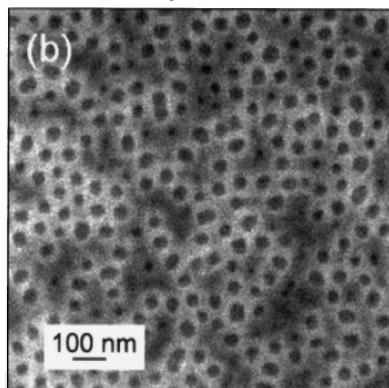
Particle Size and Spacing Control

Utilize diblock copolymer templates developed for nano-scale patterning on silicon

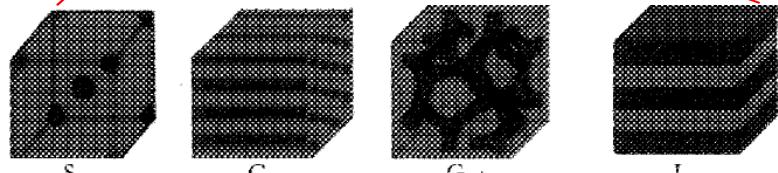
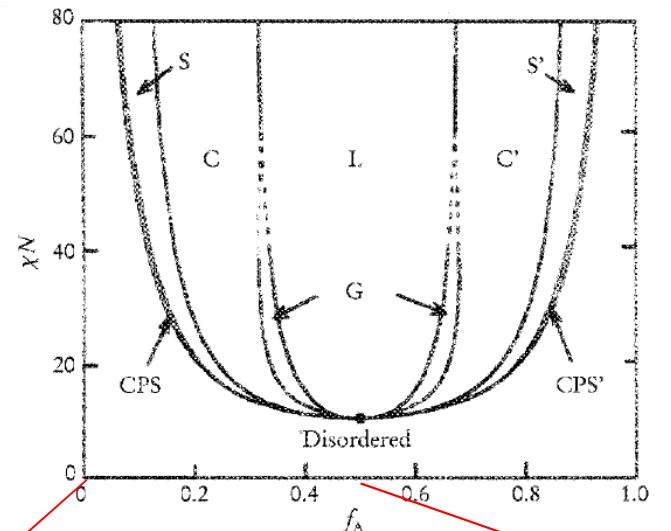
$M_n=67100$ g/mol
 \varnothing 24 nm, pitch 50 nm



$M_n=131800$ g/mol
 \varnothing 40 nm, pitch 70 nm



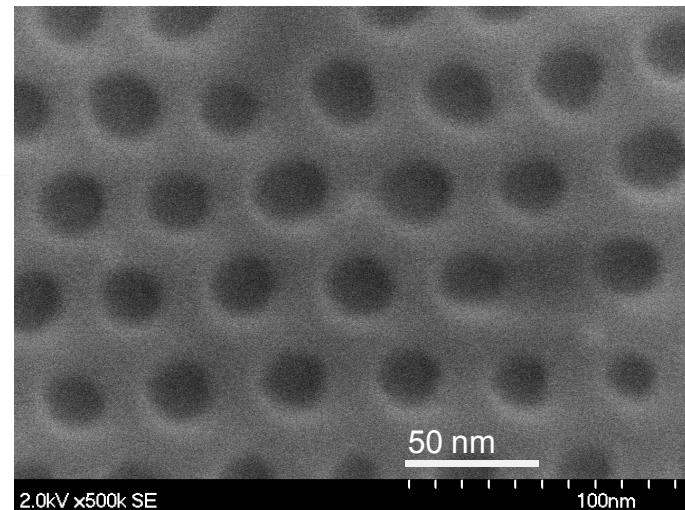
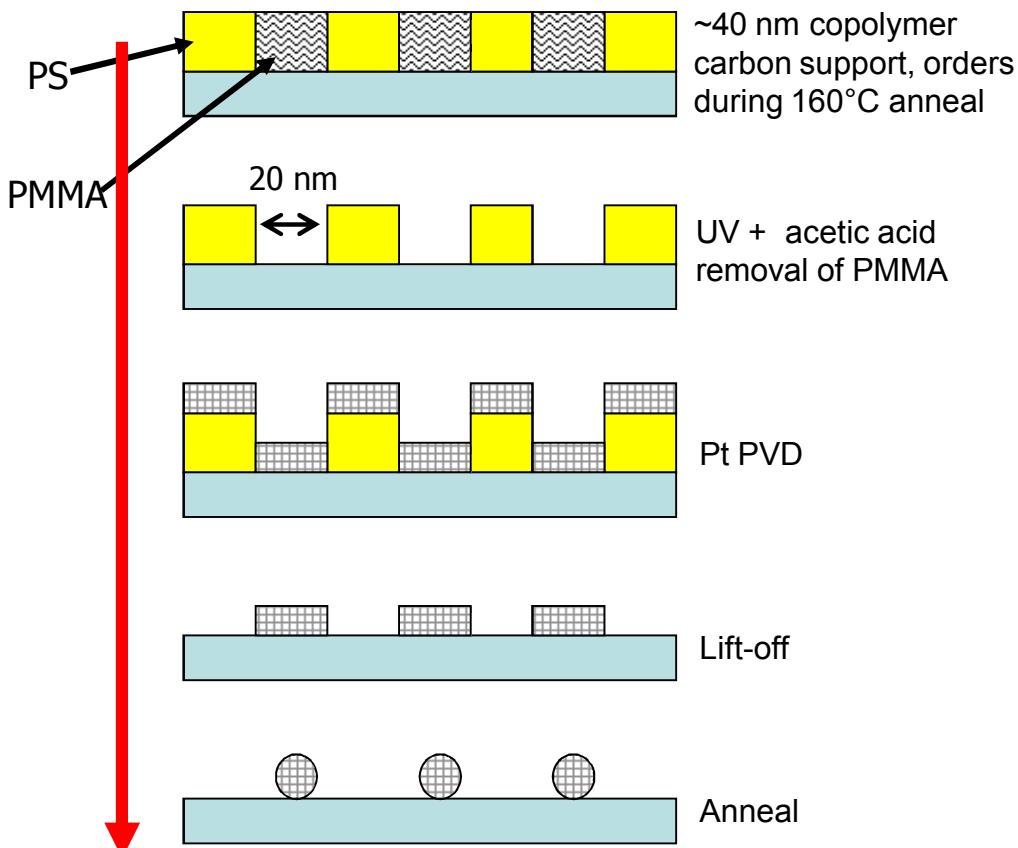
SEM images of the exposed and developed polymer template for different PS-PMMA diblock copolymer molecular weights, demonstrating how pore size and spacing can be controlled.



Template Process

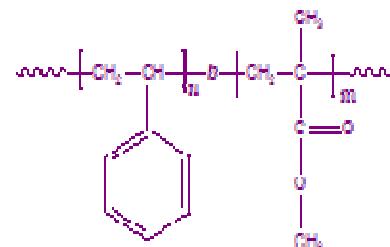
20 nm Pores in Polystyrene on Si Wafer

- Thin random brush copolymer is first created on substrate by spin coating from toluene solution. Brush bonding occurs to hydroxyl groups.
- Block co-polymer is then added by spin coating a 1% PS-b-PMMA solution in toluene



101.5 kDa (68.0-b-33.5)
67.1 kDa (46.1-b-21.0)
31.5 kDa (21.5-b-10.0)

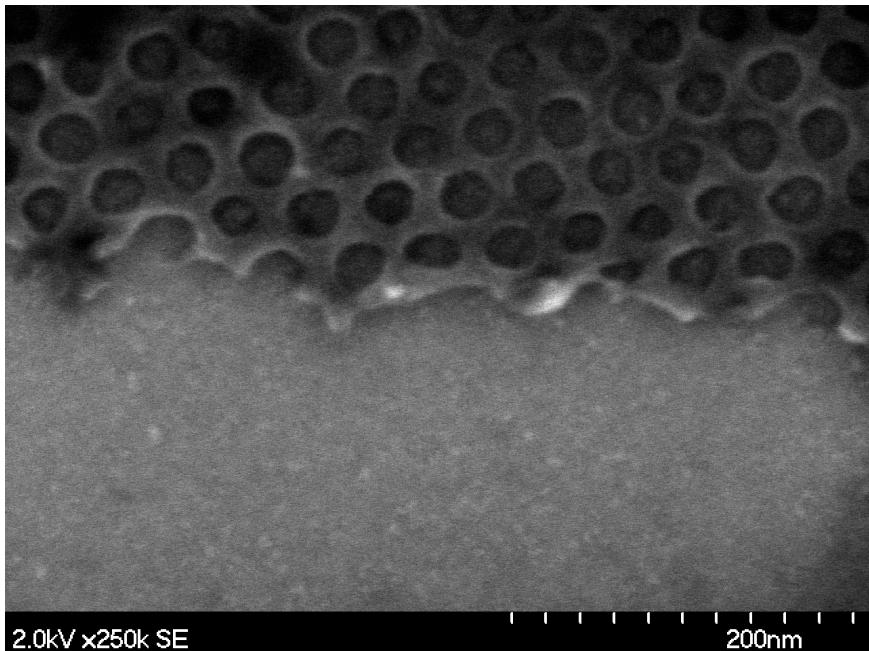
Poly(styrene-b-methyl methacrylate)



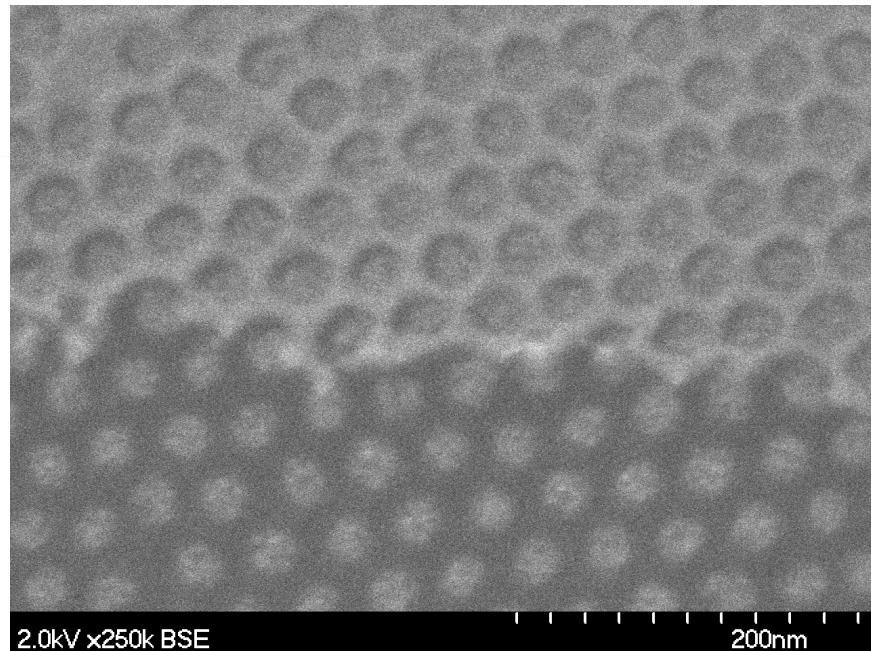
Template Results

Pt Lift-Off

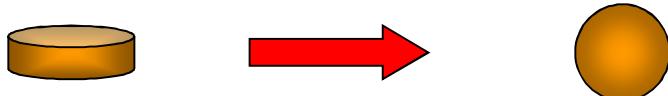
SE



BSE



- Partial lift-off of PS template after 5 minutes in toluene with ultra-sonic agitation.
- 20 nm islands ~ 1 ML thick, visible in lifted areas



$$\text{Volume of Cylinder} = h(\pi D^2)/4 \rightarrow \text{Sphere} = (\pi d^3)/6$$

(5 nm particles from 20nm pores, $h=0.21$ nm $\sim 0.44 \mu\text{g}/\text{cm}^2$)

Particle Size Control

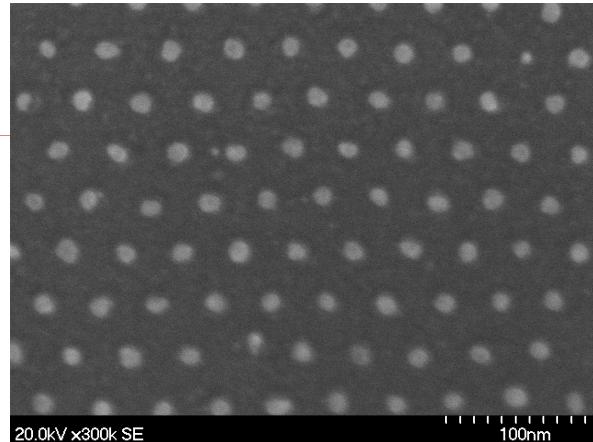
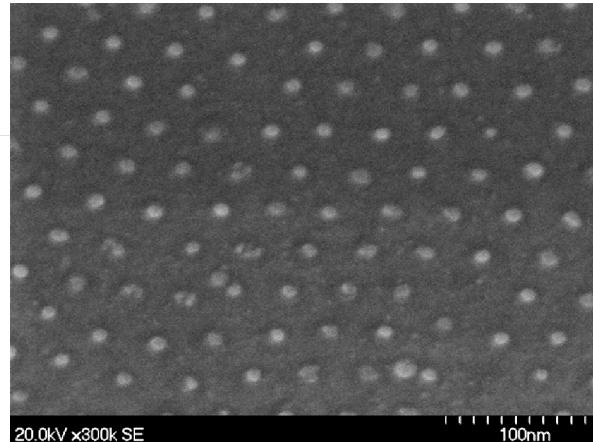
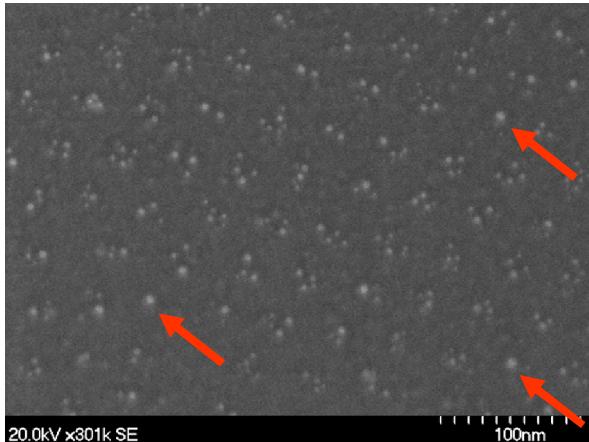
Size Control Demonstrated on Silicon



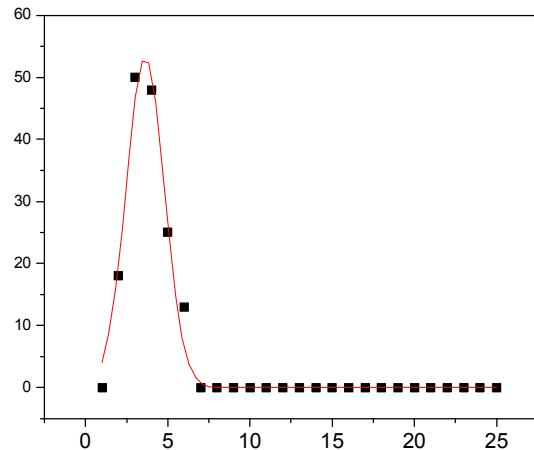
700°C



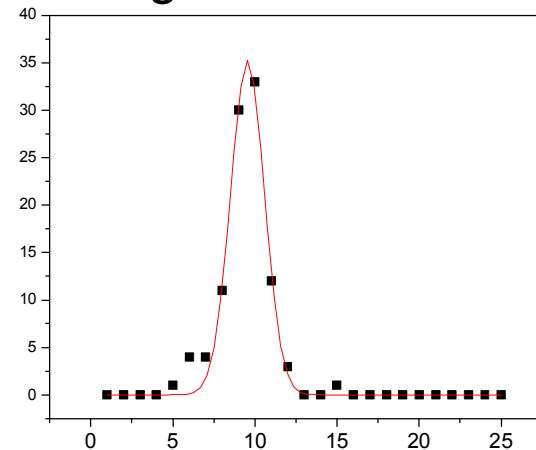
Polymer Template with 20 nm pores limited to > 7nm particles



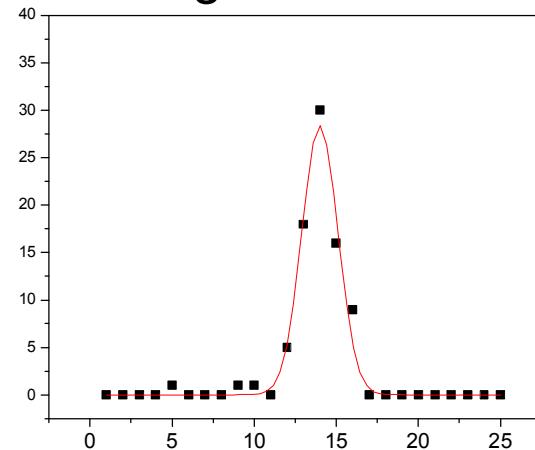
1.3 $\mu\text{g}/\text{cm}^2$ ~ 2ML
exp d = 7.1 nm
avg = 3.6 nm



3.6 $\mu\text{g}/\text{cm}^2$
exp d = 10.1 nm
avg = 9.6 nm



9.7 $\mu\text{g}/\text{cm}^2$
exp d = 14 nm
avg = 14.0 nm

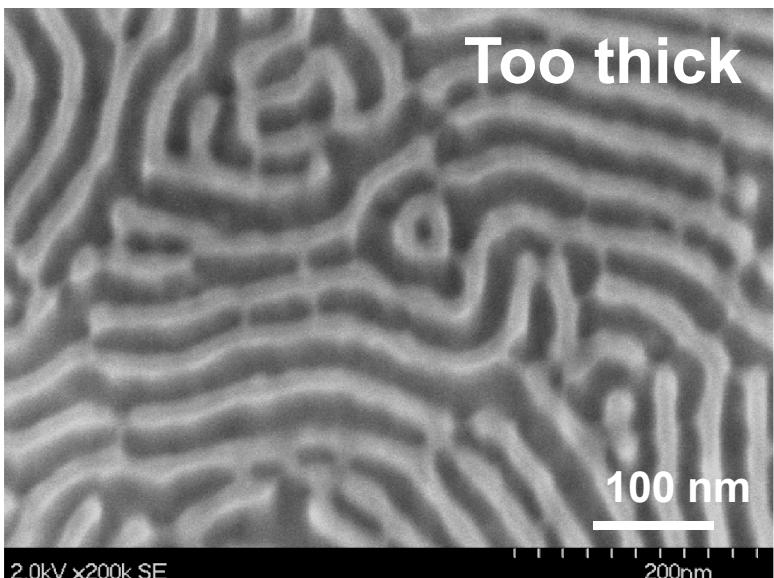
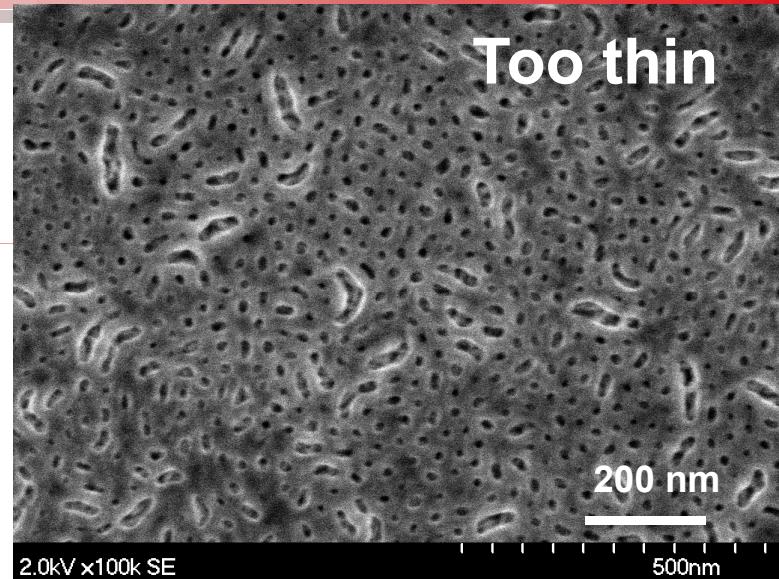
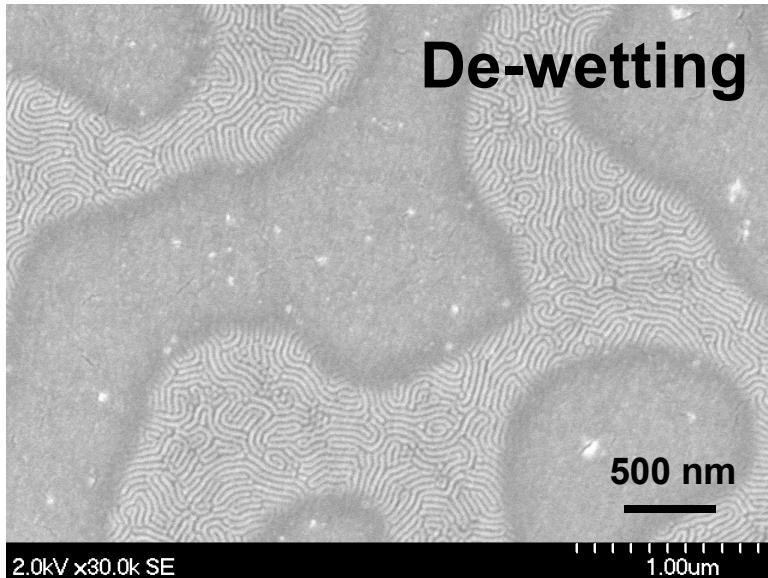


Template on Glassy Carbon

Polymer challenges on small electrode

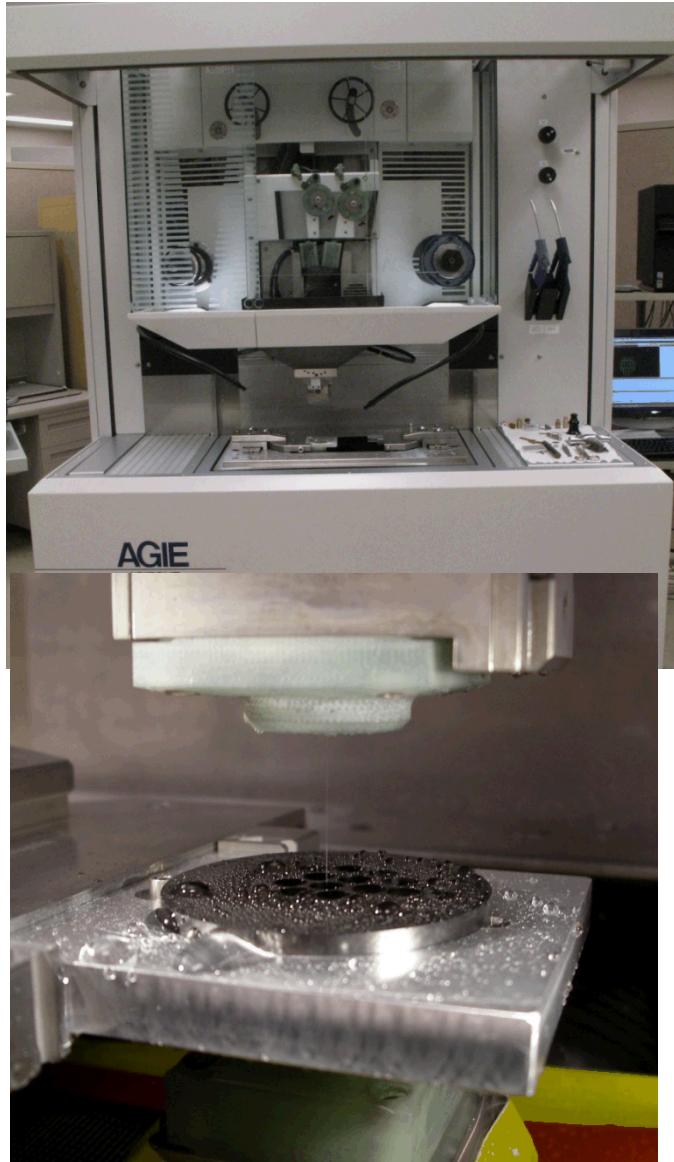
Application to 5mm glassy carbon electrodes has been challenging

*Spin uniformity on small size
Adhesion of random brush layer*



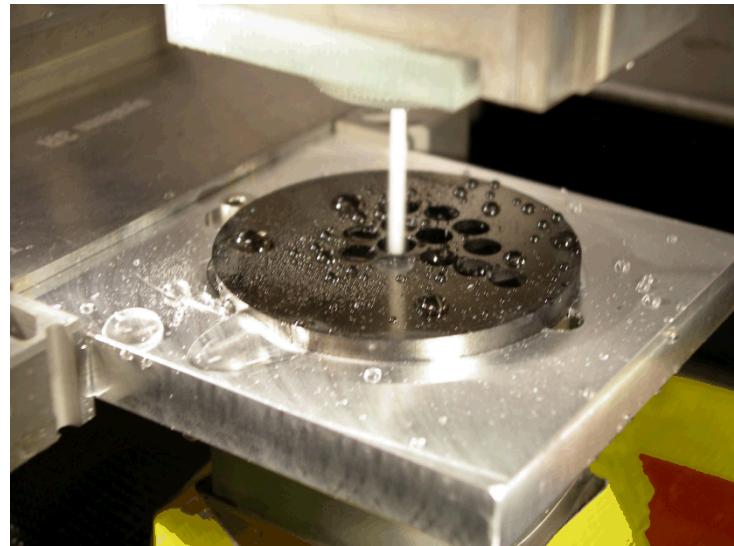
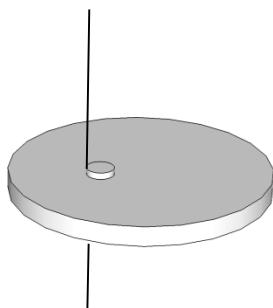
µWire EDM

Glassy carbon wafer for polymer processing



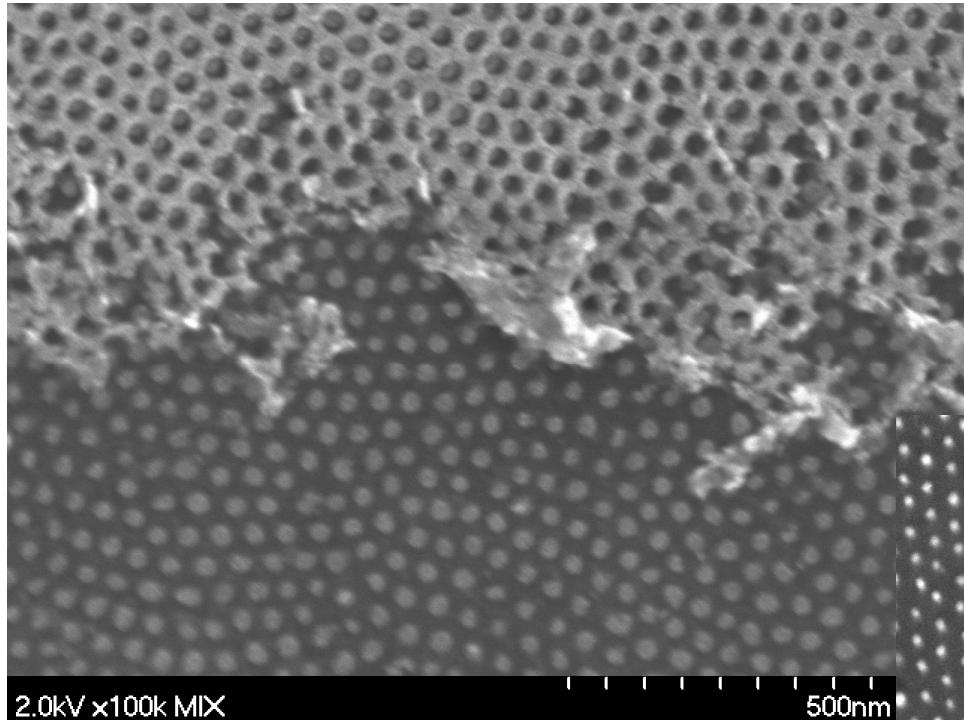
Micro-Wire Electrical Discharge Machining (EDM) using a 50 µm tungsten wire

5 mm electrodes cut from a glassy carbon wafer, 50 mm diameter, after application of polymer template



Pt Array on Glassy Carbon

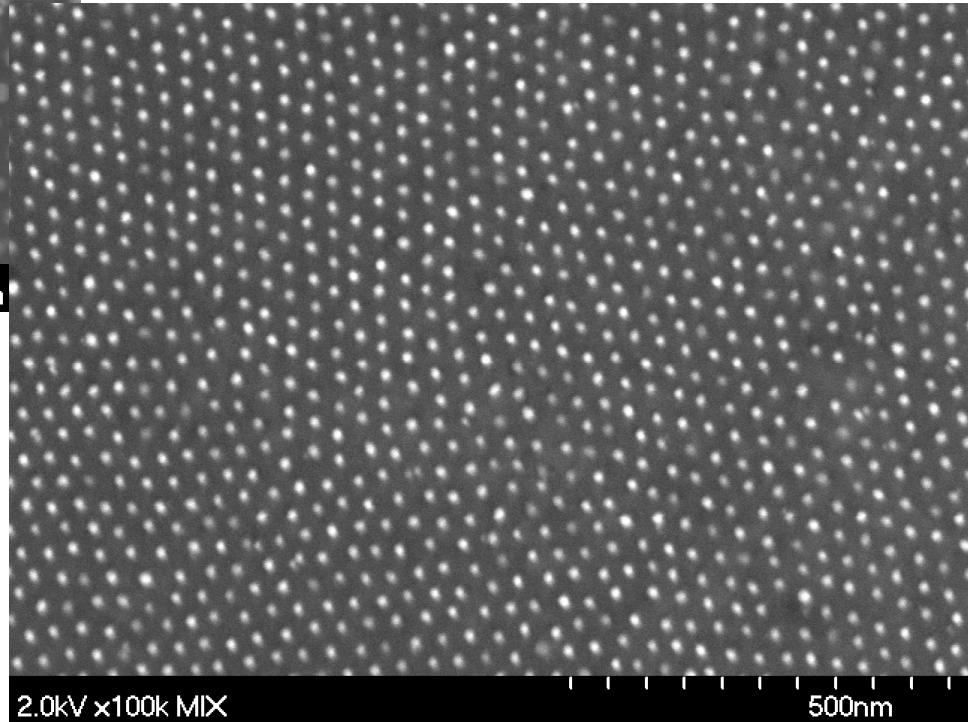
X-linked random mat on carbon



During Lift-Off in
NMP at 100°C

Cross-linked random polymer mat
created by Univ. of Wisconsin Prof.
Nealey's group

10nm particles after 800°C

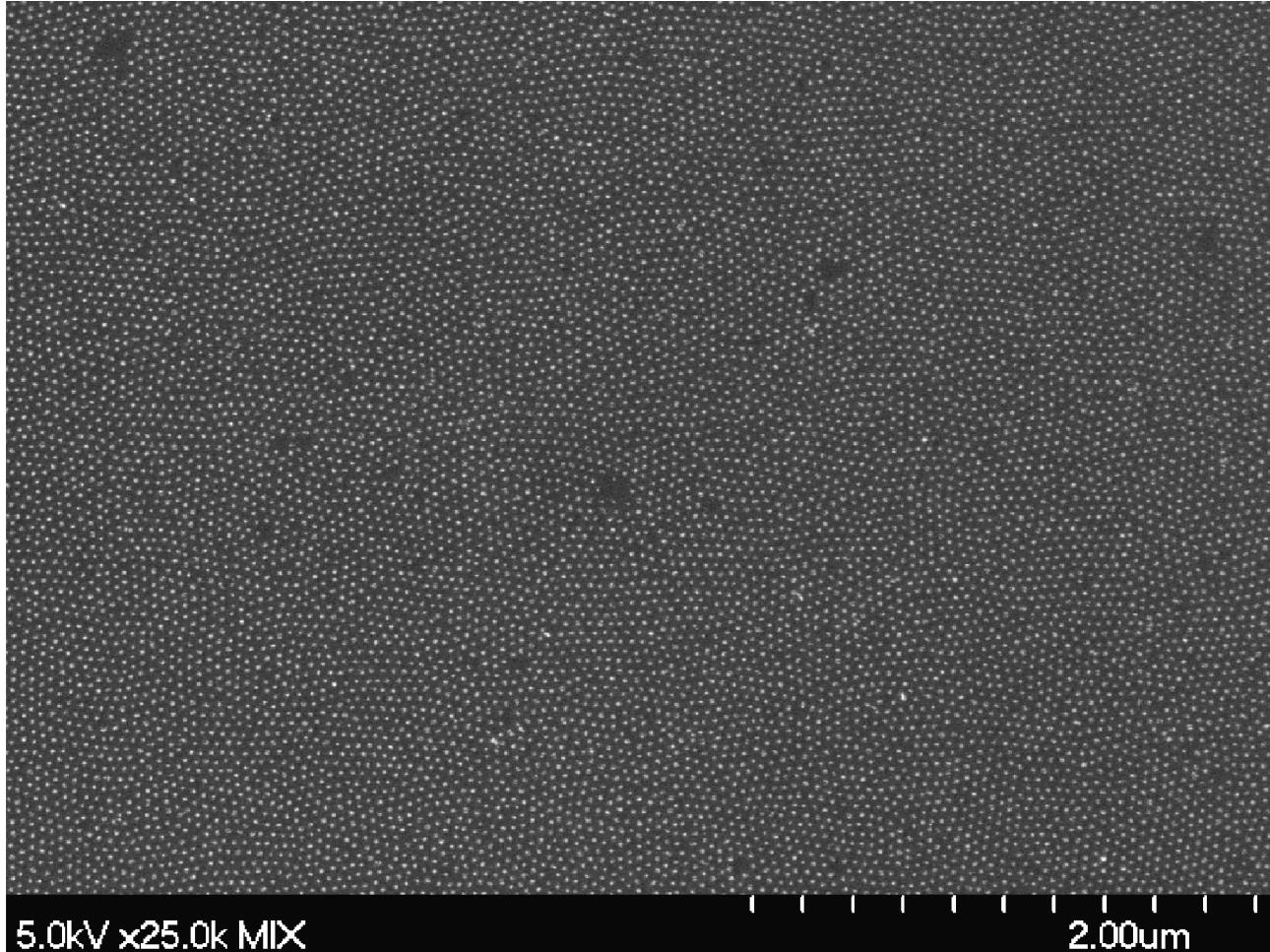


After Lift-Off and
800°C Anneal

Nano-Particle Array on GC Electrode

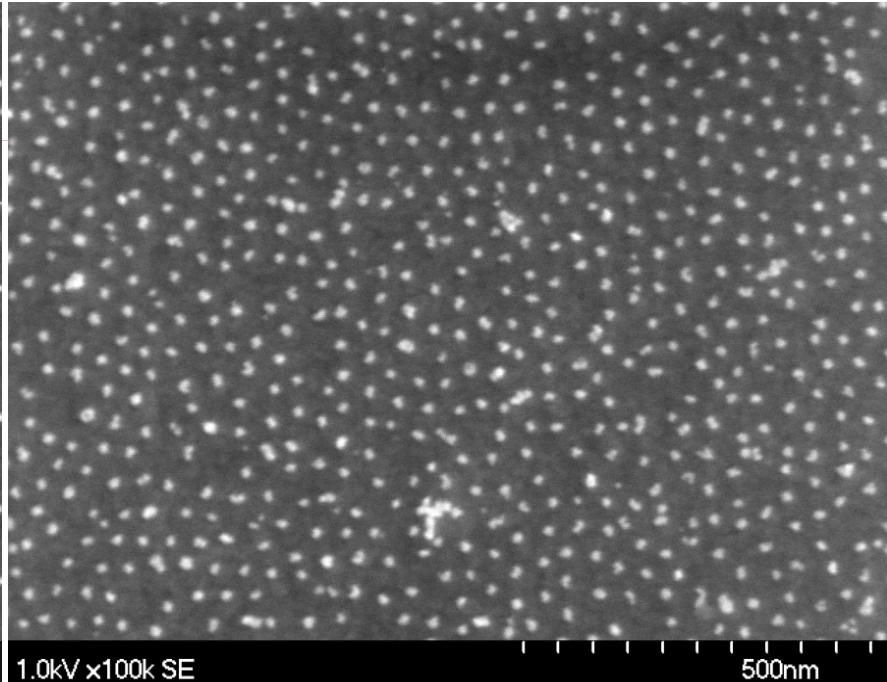
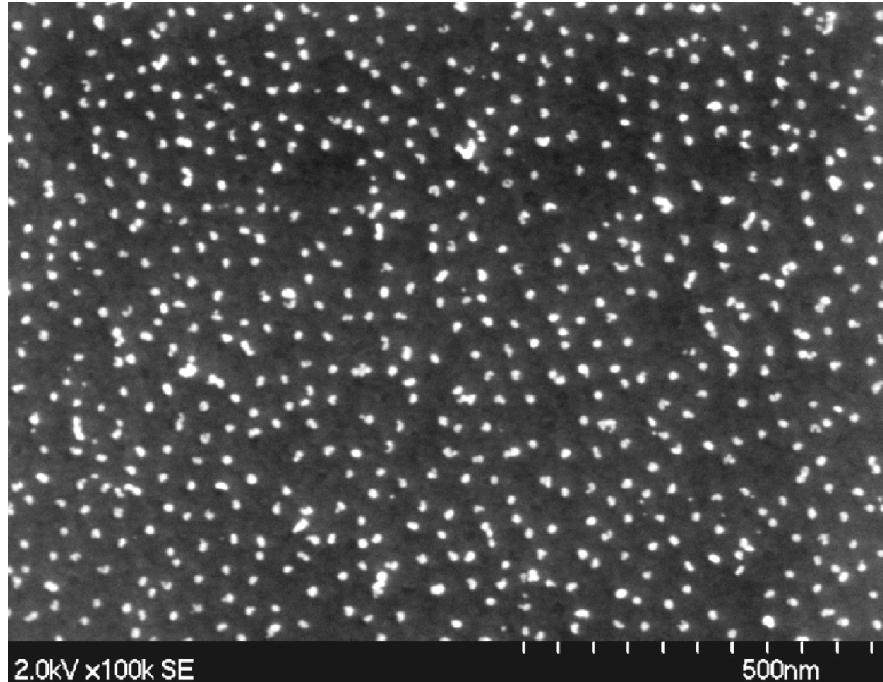
Uniformity to electrode edge

Ordering visible over large area (entire surface covered with only minor defects)



Conditioning CVs on Pt Array

Pt particle agglomeration from detachment

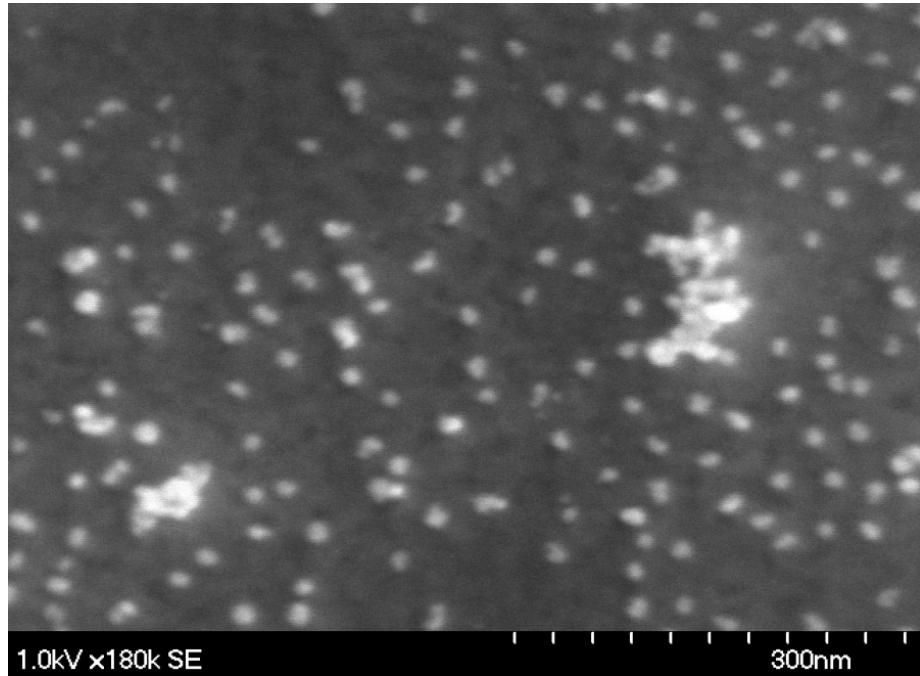


Agglomeration from detachment
- clusters not next to missing particles

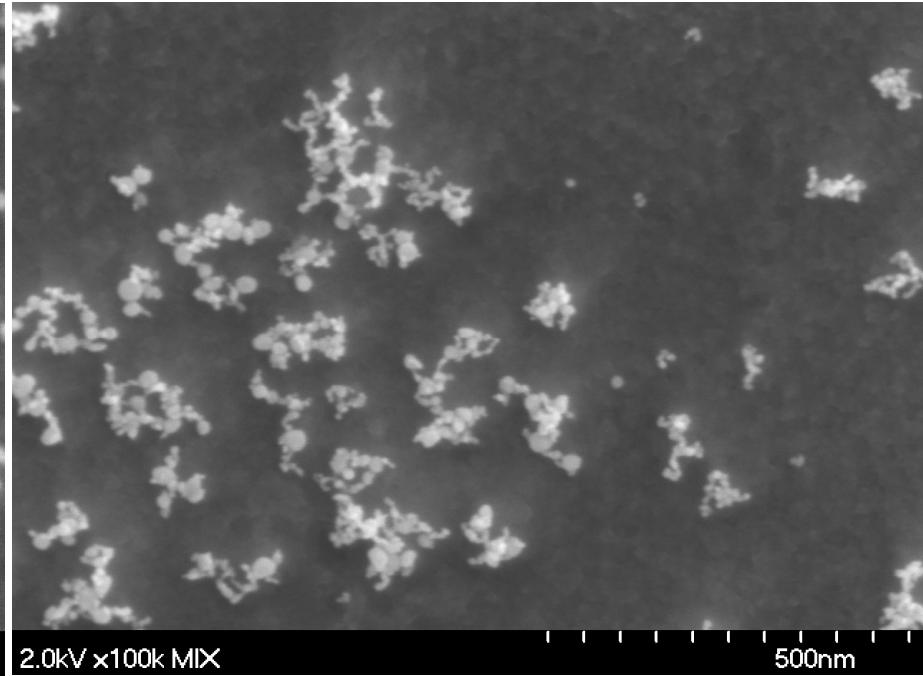
Initial Conditioning: 0 – 1.4V_{RHE} 500mV/s (40 cycles)
in Ar purged 0.1M HClO₄

Pt particle Agglomeration

Significant agglomeration in some regions



Particle agglomeration & disorder in particle array



Particle clusters slowly begin to sinter
Expect future PSD to be log-normal

Conclusions

- Model electrode structures have been developed using PVD Pt on RDE electrodes
- Cycling between RDE experiments and SEM imaging demonstrated without damaging electrode structures
- Catalyst degradation mechanisms by Ostwald ripening, dissolution and particle detachment/agglomeration observed
- Template approach developed for application of catalytic particles to glassy carbon electrodes
 - control of particle size and spacing
 - Smaller pore templates will be required for particles $< 7\text{nm}$

Acknowledgements

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NSF I/UCRC program TIE supplement**

The University of
New Mexico



Sandia National Laboratories



Sandia is a multiprogram laboratory operated by Sandia Corporation, a Lockheed Martin Company, for the United States Department of Energy's National Nuclear Security Administration under contract DE-AC04-94AL85000.